

CERTIFICATE OF COMPLIANCE

Product covered:

- IC in bare die,
- IC in bare die with solder or gold bumps,
- IC assembled in plastic package DIP, SOIC, QFN, PSOP, PLCC, QFP, TSSOP, SOT, SC-70, EMDFN,

RoHS – Directive 2011/65/EU and its amendments, including the amendment 2015/863/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment,

EM Microelectronic certifies that to the best of their knowledge and to date, the products stated above do not contain any of the substances listed below in concentration levels specified in the Directive 2015/863/EU.

Lead (Pb): <1000 ppm
Mercury (Hg): <1000 ppm
Cadmium (Cd): <100 ppm
Hexavalent Chromium (Cr VI) <1000 ppm
Polybrominated Biphenyls (PBB): <1000 ppm
Polybrominated Diphenyl Ethers (PBDE): <1000 ppm
Bis(2-ethylhexyl) Phthalate (DEHP) : <1000 ppm
Butyl benzyl Phthalate (BBP): <1000 ppm
Dibutyl Phthalate (DBP): <1000 ppm
Diisobutyl Phthalate (DIBP): <1000 ppm

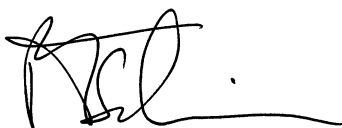
"Halogen Free" - IEC 61249-2-21:2003.

EM Microelectronic certifies that to the best of their knowledge and to date, the products stated above do not contain brominated and chlorinated compounds above the threshold level for each homogeneous material within the part/product as per IEC 61249-2-21:2003.

Chlorine (Cl): <900 ppm
Bromine (Br): <900 ppm
Total halogens (limited to Br + Cl): <1500 ppm

Date: 25.01.2019

EM MICROELECTRONIC-MARIN SA



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